

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please ADD claims 22-23.

Please AMEND claim 10 and 22-23 in accordance with the following:

Claims 1-9 (Cancelled)

10. (Currently Amended) A method, comprising:

connecting a circuit carrier to a component via contacts which place the component at a distance from the circuit carrier;

applying a foil to the component and the circuit carrier;

metallizing the foil; and

placing a solder bump as a contact element on a first side of the circuit carrier on which the component is arranged alongside the component, the solder bump projecting ~~beyond away~~ from the circuit carrier beyond a furthest point of the component from the circuit carrier.

11. (Previously Presented) A method according to claim 10, wherein said metallizing of the foil includes electrically strengthening metallization of the foil.

12. (Previously Presented) A method according to claim 11, further comprising opening a window in the foil on a side of the component facing away from the circuit carrier.

13. (Previously Presented) A method according to claim 12, wherein the component is a high-frequency component, especially an very-high frequency component.

14. (Previously Presented) A method according to claim 13, further comprising mounting a passive component on the circuit carrier.

15. (Previously Presented) A method according to claim 14, wherein said mounting of the passive component occurs on a second side opposite the first side of the circuit carrier on which the high-frequency component is connected.

16. (Previously Presented) A high frequency package, manufactured in accordance with claim 10.

17. (Previously Presented) A high frequency package, manufactured in accordance with claim 11.

18. (Previously Presented) A high frequency package, manufactured in accordance with claim 12.

19. (Previously Presented) A high frequency package, manufactured in accordance with claim 13.

20. (Previously Presented) A high frequency package, manufactured in accordance with claim 14.

21. (Previously Presented) A high frequency package, manufactured in accordance with claim 15.

22. (New) A method according to claim 10, wherein said metallizing of the foil includes galvanically strengthening metallization of the foil.

23. (New) A method accordingly to claim 23, wherein said metallizing includes electroplating.